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(54) **PRINTED CIRCUIT BOARD**

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(57) **ABSTRACT**

[Object] Provided is a printed circuit board ensuring a degree of freedom in circuit design and unlikely to cause a circuit connection failure.

[Solving Means] A middle interlayer circuit **11**, an upper surface side interlayer circuit **12**, and a lower surface side interlayer circuit **13** are formed from a connection surface-less integral conductor. In addition, a connection surface **33** between the upper surface side interlayer circuit **12** and an upper surface side surface layer circuit **14** and a connection surface **34** between the lower surface side interlayer circuit **13** and a lower surface side surface layer circuit **15** lack a connection surface in a plate thickness direction, and thus a satisfactory connection state is achieved. Accordingly, a first circuit **10** is unlikely to cause a connection failure. In addition, the upper surface side interlayer circuit **12** and the lower surface side interlayer circuit **13** can be disposed at misaligned positions in the plane direction of the printed circuit board, and thus the degree of freedom in circuit design increases. Plane circuits **24** and **16** not connected to the first circuit can be disposed with insulating layers **31** and **32** sandwiched below the upper surface side interlayer circuit **12** or above the lower surface side interlayer circuit **13**.